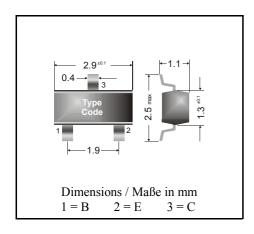




PNP Surface mount Si-Epitaxial PlanarTransistors Si-Epitaxial PlanarTransistoren für die Oberflächenmontage

PNP



Power dissipation – Verlustleistung 250 mW

Plastic case SOT-23

Kunststoffgehäuse (TO-236)

Weight approx. – Gewicht ca. 0.01 g

Plastic material has UL classification 94V-0 Gehäusematerial UL94V-0 klassifiziert

Standard packaging taped and reeled Standard Lieferform gegurtet auf Rolle

Maximum ratings $(T_A = 25^{\circ}C)$

Grenzwerte $(T_A = 25^{\circ}C)$

			BCW 67	BCW 68	
Collector-Emitter-voltage	B open	- V _{CE0}	32 V	45 V	
Collector-Base-voltage	E open	- V _{CB0}	45 V	60 V	
Emitter-Base-voltage	C open	- V _{EB0}	5 V		
Power dissipation – Verlustleistung		P _{tot}	250 mW ¹)		
Collector current – Kollektorstrom (DC)		- I _C	800 mA		
Peak Collector current – Kollektor-Spitzenstrom		- I _{CM}	1000 mA		
Base current – Basis-Spitzenstrom		- I _B	100 mA		
Peak Base current – Basis-Spitzenstrom		- I _{BM}	200 mA		
Junction temperature – Sperrschichttemperatur		T_{j}	150°C		
Storage temperature – Lagerungstemperatur		T_{S}	- 65+ 150°C		

Characteristics $(T_j = 25^{\circ}C)$

Kennwerte $(T_j = 25^{\circ}C)$

			Min.	Typ.	Max.
Collector-Base cutoff current – Kollektorreststrom					
$I_E = 0$, - $V_{CB} = 32 \text{ V}$	BCW 67	- I _{CB0}	_	_	20 nA
$I_E = 0$, - $V_{CB} = 32 \text{ V}$, $T_j = 150^{\circ}\text{C}$		- I _{CB0}	_	_	20 μΑ
$I_E = 0$, - $V_{CB} = 45 \text{ V}$	BCW 68	- I _{CB0}	_	_	20 nA
$I_E = 0$, - $V_{CB} = 45 \text{ V}$, $T_j = 150^{\circ}\text{C}$		- I _{CB0}	_	-	20 μΑ
Emitter-Base cutoff current – Emitterreststrom					
$I_C = 0$, - $V_{EB} = 4 \text{ V}$		- I _{EB0}	_	_	20 nA

¹) Mounted on P.C. board with 3 mm² copper pad at each terminal Montage auf Leiterplatte mit 3 mm² Kupferbelag (Lötpad) an jedem Anschluß

01.11.2003



Characteristics $(T_i = 25^{\circ}C)$

Kennwerte $(T_i = 25^{\circ}C)$

Characteristics $(1_j = 25)$			Kennwerte $(1_j = 25 \text{ C})$			
			Min.	Тур.	Max.	
Collector saturation volt. – Kollektor-Sättigungsspg. 1)						
$-I_{\rm C} = 100 \text{ mA}, -I_{\rm B} = 10 \text{ mA}$		- V _{CEsat}	_	_	300 mV	
$I_{\rm C} = 500 \text{ mA}, -I_{\rm B} = 500 \text{ mA}$	0 mA	- V _{CEsat}	_	_	700 mV	
Base saturation voltage –	Basis-Sättigungsspann					
$-I_{\rm C} = 100 \text{ mA}, -I_{\rm B} = 10 \text{ mA}$		- V _{BEsat}	_	_	1.25 V	
$-I_{\rm C} = 500 \text{ mA}, -I_{\rm B} = 50 \text{ mA}$		- V _{BEsat}	_	_	2 V	
DC current gain – Kollek	tor-Basis-Stromverhälti					
	BCW 67A / 68F	h_{FE}	35	_	_	
- $V_{CE} = 10 \text{ V}$ - $I_{C} = 100 \mu \text{ mA}$	BCW 67B / 68G	h_{FE}	50	_	_	
- 1 _C – 100 μ mA	BCW 67C / 68H	\mathbf{h}_{FE}	80	_	_	
	BCW 67A / 68F	h_{FE}	75	_	-	
$- V_{CE} = 1 V$ $- I_{C} = 10 \text{ mA}$	BCW 67B / 68G	\mathbf{h}_{FE}	120	_	_	
- I _C – 10 IIIA	BCW 67C / 68H	\mathbf{h}_{FE}	180	_	_	
- $V_{CE} = 1 \text{ V}$ - $I_{C} = 100 \text{ mA}$	BCW 67A / 68F	\mathbf{h}_{FE}	100	160	250	
	BCW 67B / 68G	h_{FE}	160	250	400	
	BCW 67C / 68H	\mathbf{h}_{FE}	250	350	630	
- $V_{CE} = 2 V$ - $I_{C} = 500 \text{ mA}$	BCW 67A / 68F	$h_{ ext{FE}}$	35	_	_	
	BCW 67B / 68G	$\mathbf{h}_{ ext{FE}}$	60	_	_	
	BCW 67C / 68H	\mathbf{h}_{FE}	100	_	_	
Gain-Bandwidth Product – Transitfrequenz						
$-V_{CE} = 5 \text{ V}, -I_{C} = 50 \text{ mA}, f = 100 \text{ MHz}$		$f_{\scriptscriptstyle T}$	_	200 MHz	_	
Collector-Base Capacitan	nce – Kollektor-Basis-K	apazität				
$-V_{CB} = 10 \text{ V}, I_{E} = i_{e} = 0, f = 1 \text{ MHz}$		C_{CB0}	_	6 pF	_	
Emitter-Base Capacitance	e – Emitter-Basis-Kapaz	zität				
$-V_{EB} = 0.5 \text{ V}, I_{C} = i_{c} = 0, f = 1 \text{ MHz}$		C_{EB0}	_	60 pF	_	
Thermal resistance junction to ambient air Wärmewiderstand Sperrschicht – umgebende Luf		ft	R_{thA}		420 K/W ²)	
Recommended complementary NPN-transistors Empfohlene komplementäre NPN-Transistoren		ВС	BCW 65, BCW 66			
	DOW CEA	DA T		ND DOW	(70 DC	
Marking – Stempelung		BCW $67A = DA$ BCW $67B = DB$ BCW $67C = DC$				
	BCW 68F =	DF E	3CW 68G = D	DG BCW	68H = DH	

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Tested with pulses t_p = 300 μs, duty cycle ≤ 2% - Gemessen mit Impulsen t_p = 300 μs, Schaltverhältnis ≤ 2%
 Mounted on P.C. board with 3 mm² copper pad at each terminal Montage auf Leiterplatte mit 3 mm² Kupferbelag (Lötpad) an jedem Anschluß